

Product brief

Automotive EasyPACK™ 2B EDT2

Power module solution for inverters up to 50 kW

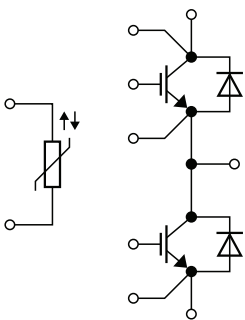
Infineon's new AQG324 qualified EasyPACK™ 2B EDT2 is a flexible and scalable power module solution optimized for inverter applications of hybrid and electric vehicles. With this half-bridge module you can reach a maximum performance of up to 50 kilowatts and 230 Arms, depending on inverter conditions.

It combines the best of Infineon's technologies to maximize efficiency and cost-effectiveness: three EasyPACK™ 2B half-bridge modules are 30 percent smaller than one HybridPACK™ 1 B6-bridge module. EasyPACK™ 2B contains the latest EDT2 chip technology, which allows for higher efficiency at low-load conditions. Our EDT2 chip is able to ensure significantly less losses than the current competing products, even outperforming Infineon's previous chip generation by 20 percent. Furthermore, one of the distinctive features of the EasyPACK™ is the plug-and-play approach, which makes module integration considerably easier. Infineon's PressFIT contact technology allows in fact for reduced mounting time, offering not only a very compact but also cost-attractive design. That means compared to classical through-hole discrete packages as well as HybridPACK™ 1, no soldering of the pins is required anymore.

Applications

- > Traction inverter
- > Electric Vehicle (EV) drivetrain system
- > Commercial, construction and agriculture vehicles
- > Motor drives

Block diagram



Key features

- > **Electrical**
 - Blocking voltage 750 V
 - Low V_{CEsat}
 - Low switching losses
 - Low Q_g and C_{rss}
 - Low inductive design
 - $T_{vj op} = 150^\circ C$
- > **Mechanical**
 - PressFIT pins for the signal terminals
 - High creepage and clearance distances
 - Integrated NTC temperature sensor
 - RoHS compliant





Key benefits

- > **Flexible half-bridge solution** enabling different inverter geometries and further motor integration
- > **Easy and compact design** (Integrated module solution with optimized thermal management, 30% smaller foot print than HybridPACK™ 1)
- > **High reliability** (short circuit ruggedness, increased blocking voltage, high power cycling capability, high creepage and clearance distances)
- > Power module with **integrated isolation and NTC**
- > **Easy and fast assembly** through PressFIT contact technology (solder-less mounting)
- > Automotive qualified according **AQG 324**





Automotive EasyPACK™ 2B EDT2

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Our customers chose Easy power module because of

- 
Cost-effective assembly
 Easy PCB mounting (PressFit)
- 
Easy design
 Highly integrated “all-in-one” module solution with optimized thermal capabilities
- 
Reliability
 Integrated isolation/creepage
- 
Flexibility
 Platform for different technologies and topologies

Our customers chose Infineon EasyPACK™ because of

- 
High volume manufacturing experience
 Over 50 million EasyPACK™ sold
- 
Seamless traceability
 Given for every individual module
- 
Leader in quality
 - > Field proven quality
 - > Reuse of successful technologies
- 
Technical leader
 Market innovator with extensive local technical support

Order information

Type	Description	Electrical characteristics	OPN
FF300R08W2P2_B11A	Automotive EasyPACK™ 2B	750 V / 300 A	FF300R08W2P2B11ABOMA1

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